

#### General purpose medium power amplifier or switch in bare die form Complement to PNP BC307B

## Features:

- Low saturation voltage
- Well suited for amplifier applications
- High reliability gold back metal
- High reliability tested grades for Military + Space

# Ordering Information:

The following part suffixes apply:

- No suffix MIL-STD-750 /2072 Visual Inspection
- "H" MIL-STD-750 /2072 Visual Inspection + MIL-STD-38534 Class H LAT
- "K" MIL-STD-750 /2072 Visual Inspection + MIL-STD-38534 Class K LAT

LAT = Lot Acceptance Test.

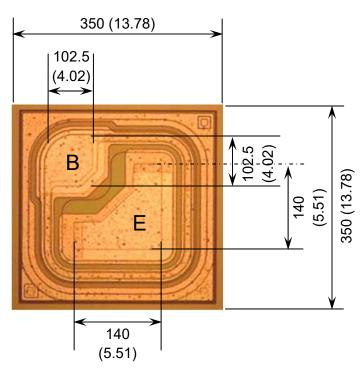
For further information on LAT process flows see below.

www.siliconsupplies.com\quality\bare-die-lot-qualification

# Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape Specific request
- Unsawn Wafer Specific request
- With additional electrical selection Specific request
- Sawn as pairs or adjacent pair pick Specific request

## Die Dimensions in µm (mils)



E = EMITTER B = BASE

**DIE BACK =** COLLECTOR

# **Mechanical Specification**

Die Size (Excluding Saw Street)	350 x 350 13.78 x 13.78	µm mils	
Base Pad Size	102.5 x 102.5 4.02 x 4.02	μm	
Emitter Pad Size	96 x 96 5.51 x 5.51	mils	
Die Thickness	230 (±15) 9.06 (±0.59)	µm mils	
Top Metal Composition	Al - 1.3µm		
Back Metal Composition	AuAs - 0.9µm		



**Rev 1.0** 

08/01/19



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#### Absolute Maximum Ratings T<sub>A</sub> = 25°C unless otherwise stated

<b>o</b>				
PARAMETER	SYMBOL	VALUE	UNIT	
Collector-Base Voltage	V <sub>CBO</sub>	50	V	
Collector-Emitter Voltage	V <sub>CEO</sub>	45	V	
Emitter-Base Voltage	V <sub>EBO</sub>	6	V	
Collector Current	Ic	100	mA	
Junction Temperature	TJ	150	°C	
Storage Temperature	T <sub>stg</sub>	-55 to 150	°C	

## **Electrical Characteristics** $T_A = 25^{\circ}C$ unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS		·				
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	$I_{\rm C} = 10 \mu A, I_{\rm E} = 0$	50	-	-	V
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	$I_{\rm C}$ = 10mA, $I_{\rm B}$ = 0	45	-	-	V
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	$I_{\rm E}$ = 10µA, $I_{\rm C}$ = 0	6	-	-	V
Collector Cut-off Current	I <sub>CBO</sub>	$V_{CB} = 40V, I_E = 0$	-	-	15	nA
ON CHARACTERISTICS						
Forward-Current Transfer Ratio <sup>1</sup>	h <sub>FE</sub>	$V_{CE} = 5V, I_{C} = 2mA$	200	230	450	-
		$V_{CE} = 5V, I_{C} = 10\mu A$	40	150	-	-
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 10mA, I <sub>B</sub> = 0.5mA	-	70	250	mV
		I <sub>C</sub> = 100mA, I <sub>B</sub> = 5mA	-	200	600	mV
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	I <sub>C</sub> = 10mA, I <sub>B</sub> = 0.5mA	-	700	830	mV
		I <sub>C</sub> = 100mA, I <sub>B</sub> = 5mA	-	950	1050	mV
Base-Emitter On Voltage	V <sub>BE(on)</sub>	$I_{C} = 2mA, V_{CE} = 5V$	550	650	700	mV
		I <sub>C</sub> = 10mA, V <sub>CE</sub> = 5V	-	-	770	mV
SMALL SIGNAL CHARACTERISTICS	2					
Transition Frequency <sup>3</sup>	fT	V <sub>CE</sub> = 5V, I <sub>C</sub> = 10mA, f = 100MHz	150	300	-	MHz
Small-Signal Current Gain	h <sub>fe</sub>	$V_{CE}$ = 5V, I <sub>C</sub> = 2mA, f = 1 kHz	240	330	500	
Output Capacitance	C <sub>obo</sub>	V <sub>CB</sub> = 10V, I <sub>E</sub> = 0, f = 1MHz	-	2.5	4.5	pF
Input Capacitance	C <sub>ibo</sub>	V <sub>BE</sub> = 10V, I <sub>C</sub> = 0, f = 1MHz	-	9	-	pF
Noise Figure	NF	$V_{CE}$ = 5V, I <sub>C</sub> = 200µA, f = 1KHz, R <sub>G</sub> =2KΩ	-	2	10	dB

Note 1: Pulse Test: Pulse Width ≤ 300  $\mu$ s, Duty Cycle ≤ 2%

Note 2: Not production testing in die form. Characterized by chip design and tested in package

Note 3:  $f_{\rm T}$  is defined as the frequency at which  $~|h_{\rm fe}|$  extrapolates to unity.





1000

100

10

1 └ 0.1

V<sub>CF</sub> = 5V

fr, CURRENT GAIN-BANDWIDTH PRODUCT

# NPN Transistor Bare Die – BC107B

## Typical Characteristics T<sub>A</sub> = 25°C unless otherwise stated

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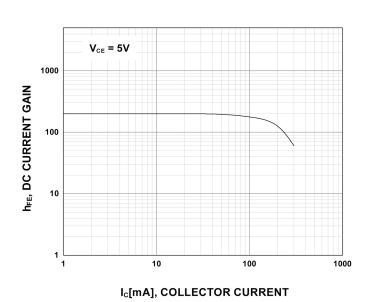
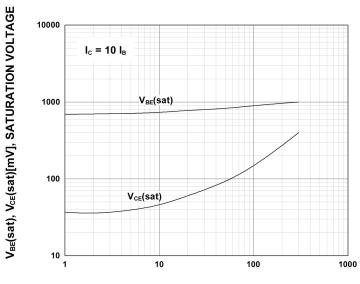
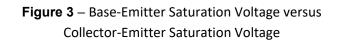
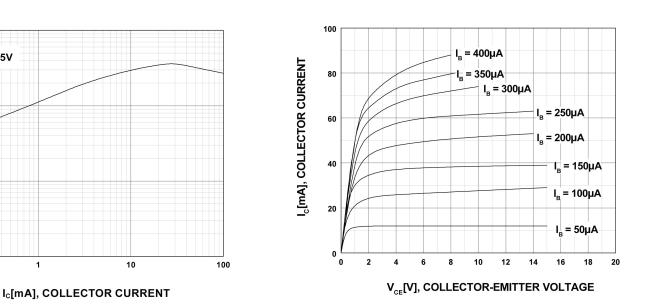


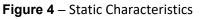
Figure 1 – DC Current Gain











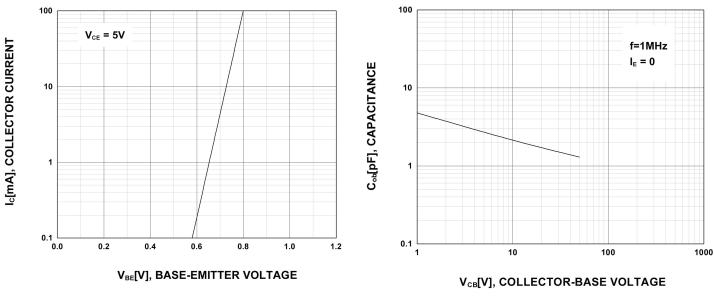
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Figure 3 – Current Gain Bandwidth Product





## Typical Characteristics T<sub>A</sub> = 25°C unless otherwise stated



**Figure 5** – Transfer Characteristic

Figure 6 – Output Capacitance

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